

SLOT HOLES: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED SIZE	ROTATION	PLATED	QTY
	787.4x43.3	90.000	NON-PLATED	4

Drill Chart: Top to Bottom					
All Units are in MILS					
Figure	Finished Size	Rotation	Plated	Qty	
A	12.0	-	Plated	546	
B	31.5	-	Plated	16	
C	35.43	-	Plated	34	
D	43.31	-	Plated	6	
E	47.24	-	Plated	8	
F	51.0	-	Plated	2	
G	55.0	-	Plated	5	
H	59.05	-	Plated	4	
I	82.68	-	Plated	2	
L	35.43	-	Non-Plated	2	
M	125.98	-	Non-Plated	6	

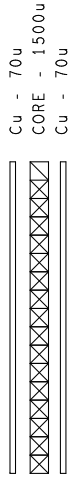
Finished Hole Tolerance - All units are in Inches -		
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter
0.008" - 0.013"	+0.002/-FHS*	+/-0.002-
0.014" - 0.063	+/-0.003	+/-0.002-
0.064" - 0.156	+/-0.004	+/-0.003-
0.157" - 0.250	+/-0.007	+/-0.004-
0.251" and up	+/-0.007	+/-0.005-
0.125"	Non Plated Only	+0.003/-0.000*

FABRICATION NOTE:

- 1-FABRICATE USING LATEST REVISION OF PC-6012A CLASS 2 OR ABOVE
- 2-FABRICATE USING MASTER ARTWORK E5V3N32F60601S1 R1 FOR CIRCUIT PATTERN  
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN  
APPROVAL FROM AN AUTHORIZED SMT/electronics REPRESENTATIVE
- 3-VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH  
APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND  
PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4-MATERIAL: FR4 ROHS COMPLIANT MINIMUM 170 C (High Tg)  
SEE "DETAIL "A"" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5-GREENE SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6-FINISH: HAL Lead Free
- 7-FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF  
OF SOLDER MASK IS ALLOWED
- 8-SILKSCREEN TO BE WHITE; NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9-THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10-ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE  
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 11-VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD  
FABRICATION-STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON  
OUTER LAYERS, FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 12-VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON  
TESTING TO PROVIDE VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION  
TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 13-REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 14-ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON  
SHORTS. APPLY TEST STAMP IN REFERENCED AREA
- 15-THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

## DETAIL "A"

LAYER BUILD UP  
(reference only)



(external Cu th are after plating)  
estimated total thickness 1650u

[illegible]